RD-ECR (Engineering Change Request)

申請人: 硬體課/賴嘉賓 表單號: 10 申請日期: 2026-06-02

Proposed Change	☐ Design modification 設計修改 ☐ Add second source 新增替代料 ☐ Material change 材料變更 ☐ Manufacturer change 製造商變更 ☐ Process sequency change 工序變更 ☐ Factory change 工廠變更 ☐ Equipment/Tooling change 設備/模具變更 ☐ Process/Method/Condition change 加工流程/方法 /條件變更 ☑ Others 其他			EC No	EC26060201
-	刪除 / 修改 , 替待料關係			Initiator	賴嘉賓(D0164)
Reason for Change	MCC物料歐盟禁用			Issue Date	2026-06-02
Model / Part No	RUP2433AMI			Requester Dept	DV11S006-產品管理部
Implementation Type	◉ 1. Immediately Change 立即切換 ○ 2. Running Change 自然切換 ○ 3. Other 其他			-	N/A
PM	曹嘉雯(D0572)	Sales	胡靜文(D0547)	Customer Approval	○ Needed ◉ Not needed
File attached 附件上傳	MCC.pdf 設計變更審查會議記錄 NXP...	Customer Sign-off Area 客戶簽核		Customer Name	Philips
Comments 會簽意見	2AAD462R13U 已切換使用3D2020EH01Y / 3D2020EH01Y181				

Material Change Description 物料變更說明

No	Subassembly	T	PartNo	Description	Qty	Location	Stock	Remark
1	2AAD462R13U	B	3DSL24PL01Y	DIODE (SL24PL,SOD123FL,SMD, MCC)	2.000	D1702,D1703		2nd : 3D2020EH01Y181 3rd : 3D2020EH01Y
1	2AAD462R13U	A	3D2020EH01Y	DIODE (PMEG2020EH,SOD123F, SMD,NXP)	2.000	D1702,D1703		2nd : 3D2020EH01Y181

Engineering Change Assessment Item List 工程變更評估項目清單

1. Application for Revision of Specification or Drawing(s) for delivery 是否有修改交貨的規格或圖面	1.Confirm	○ Yes ◉ No need
2. Standards or Regulatories impact 是否有評估適用之標準或主管機關之相關法規的申請	2.Confirm	○ Yes ◉ No need
3. Change point of PCB mounting PCBA插件位置是否變更	3.Confirm	○ Yes ◉ No need
4. PCBA Process Changes PCBA製程是否變更	4.Confirm	○ Yes (Continue checking below) ◉ No
_ 4-1) Change of Reflow temperature 迴焊溫度是否變更	4-1 Confirm	○ Yes ◉ No need
_ 4-2) Change of bonding temperature 膠合溫度是否變更	4-2 Confirm	○ Yes ◉ No need
_ 4-3) Change of Manual Soldering temperature 人工手焊工具之溫度是否變更	4-3 Confirm	○ Yes ◉ No need
_ 4-4) Change of storage condition after protection humidity package 防潮包裝完成後的儲存條件是否變更	4-4 Confirm	○ Yes ◉ No need
5. Reliability test report(Test result and data) 是否有可靠性測試報告(測試結果及數據)	5.Confirm	○ Yes ◉ No need
6. Process FMEA(Medical only) 是否有進行製程失效模式與效應分析	6.Confirm	○ Yes ◉ No need
7. Design FMEA(Medical only) 是否有進行設計失效模式與交應分析	7.Confirm	○ Yes ◉ No need
8. Risk Management(Medical only) 是否有進行風險管理評估	8.Confirm	○ Yes ◉ No need

9. Change points due to the modification 是否此修改會延伸導致其他變更點	9.Confirm	○ Yes ◉ No need
10. Initial Supply Control implements plan or result 是否有實施供料控制評估	10.Confirm	◉ Yes ○ No need
_ 10-1) Confirm the work order or order number or date for the implementation start of the engineering change 確認工程變更開始實施之工單或訂單號碼或日期	10-1 Confirm	◉ Yes ○ No need
_ 10-2) Coordinate the handling methods for related products and materials 協調相關產品及材料處理方法	10-2 Confirm	◉ Yes ○ No need
_ 10-3) Arrange th production schedule 處理生產日程之安排	10-3 Confirm	◉ Yes ○ No need
_ 10-4) Control the changed materials 變更材料之管制	10-4 Confrim	◉ Yes ○ No need
_ 10-5) Establish relevant execution control records for EC materials, register traceability data for each material 建立有關工程變更物料之相關執行管控記錄、登錄各項物料追溯性資料	10-5 Confirm	◉ Yes ○ No need
11. Training Requirement 若此一變更影響製程或檢驗，是否需要再做人員訓練	11.Confrim	○ Yes ◉ No need
12-1. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-1 Confirm	☐ QC control plan ☐ Service Manual ☐ Others ☑ Not needed
12-2. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-2 Confirm	☐ SIP ☐ SOP ☐ Others ☑ No need
12-3. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-3 Confirm	☑ MDF ☑ DMR ☐ Approval Sheet ☐ Engineering Spec ☐ Others ☑ Not needed
DIVA 鈺緯科技開發股份有限公司	版本：C	表單編號：QR-736-05

簽核列表 ◉ 表格 ○ 圖形

序號	簽核人	簽核結果	簽核意見
1	**盧俊宇** 二階主管(課/部級)	**同意** 2026-06-02 11:05	
2	**廖榮棋** DQE	**同意** 2026-06-05 08:51	
3	**曹嘉雯** PM	**同意** 2026-06-05 09:42	
3	**胡靜文** Sales	**同意** 2026-06-05 14:37	
4	**楊建勛** R&D Director [通知]	**同意** 2026-06-05 14:37	[通知]
5	**蕭玉桃** ECR-PIC人員	**否決** 2026-06-05 14:39	請補上設計變更審查會議記錄，謝謝。
6	**賴嘉賓** 重新送簽	**重新送簽** 2026-06-05 16:27	
7	**盧俊宇** 二階主管(課/部級)	**同意** 2026-06-08 08:56	
8	**廖榮棋** DQE	**同意** 2026-06-08 09:12	
9	**胡靜文** Sales	**同意** 2026-06-08 09:16	
9	**曹嘉雯** PM	**同意** 2026-06-08 09:34	
10	**楊建勛** R&D Director [通知]	**同意** 2026-06-08 09:34	[通知]

序號	簽核人	簽核結果	簽核意見
11	**蕭玉桃** ECR-PIC人員	**同意** 2026-06-08 11:14	
12	**王世炫** ECR-PE人員	**同意** 2026-06-08 11:43	
13	**林益銓** PE	**同意** 2026-06-08 11:50	
14	**黃振哲** ECR-PMC人員	**同意** 2026-06-08 11:59	
15	**邱羽萱** PMC	**同意** 2026-06-08 13:11	
16	**黃瓊玉** ECR-PD人員	**同意** 2026-06-08 13:35	
16	**李慧珊** ECR-SCM人員	**同意** 2026-06-10 08:58	
16	**吳汶浦** PD	**同意** 2026-06-17 13:38	
17	**廖映涵** [李慧珊 加簽]	**同意** 2026-06-17 15:13	
18	**李金龍** ECR-QA人員	**同意** 2026-06-17 16:14	
19	**陳泰盛** QA	**同意** 2026-06-18 09:29	
20	**楊建勛** R&D Director	**同意** 2026-06-18 09:37	
21	**蕭玉桃** ECR-PIC人員	**同意** 2026-06-18 10:10	
22	**賴嘉賓** SAP核發	**同意** 2026-06-18 10:23	